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#1	Search **Paddock G and transfer factor**	11:02:22	4

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Term: L11 and transfer adj factor

Display: 10 Documents in Display Format: - Starting with Number 1

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Search History

DATE: Monday, March 20, 2006 Printable Copy Create Case

Set Name side by side	Query	Hit Count	Set Name result set
DB=PGPB, USPT, EPAB, JPAB, DWPI; THES=ASSIGNEE; PLUR=YES; OP=ADJ			
L14	L11 and transfer adj factor	0	L14
L13	L11 and milk	1	L13
L12	L11 and colostrum	0	L12
L11	424/900	19	L11
L10	(424/85.1.CCLS)![IPC]	0	L10
L9	424/85.1.CCLS	0	L9
L8	424/900.CCLS	0	L8
L7	L6 and herpes virus	3	L7
L6	L4 and antigen adj specific	16	L6
L5	L4 and HHV	2	L5
L4	L3 and colostrum	31	L4
L3	(transfer factor)	1721	L3
L2	L1 and colostrum	2	L2
L1	Wilson G.in.	533	L1

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                  IPC reform
 NEWS  4  DEC 23  New IPC8 SEARCH, DISPLAY, and SELECT fields in USPATFULL/
                  USPAT2
 NEWS  5  JAN 13  IPC 8 searching in IFIPAT, IFIUDB, and IFICDB
 NEWS  6  JAN 13  New IPC 8 SEARCH, DISPLAY, and SELECT enhancements added to
                  INPADOC
 NEWS  7  JAN 17  Pre-1988 INPI data added to MARPAT
 NEWS  8  JAN 17  IPC 8 in the WPI family of databases including WPIFV
 NEWS  9  JAN 30  Saved answer limit increased
 NEWS 10  JAN 31  Monthly current-awareness alert (SDI) frequency
                  added to TULSA
 NEWS 11  FEB 21  STN AnaVist, Version 1.1, lets you share your STN AnaVist
                  visualization results
 NEWS 12  FEB 22  Status of current WO (PCT) information on STN
 NEWS 13  FEB 22  The IPC thesaurus added to additional patent databases on STN
 NEWS 14  FEB 22  Updates in EPFULL; IPC 8 enhancements added
 NEWS 15  FEB 27  New STN AnaVist pricing effective March 1, 2006
 NEWS 16  FEB 28  MEDLINE/LMEDLINE reload improves functionality
 NEWS 17  FEB 28  TOXCENTER reloaded with enhancements
 NEWS 18  FEB 28  REGISTRY/ZREGISTRY enhanced with more experimental spectral
                  property data
 NEWS 19  MAR 01  INSPEC reloaded and enhanced
 NEWS 20  MAR 03  Updates in PATDPA; addition of IPC 8 data without attributes
 NEWS 21  MAR 08  X.25 communication option no longer available after June 2006

 NEWS EXPRESS  FEBRUARY 15 CURRENT VERSION FOR WINDOWS IS V8.01a,
               CURRENT MACINTOSH VERSION IS V6.0c(ENG) AND V6.0Jc(JP),
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=> ile caplus
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```

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```
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COST IN U.S. DOLLARS                                SINCE FILE      TOTAL
                                                        ENTRY    SESSION
FULL ESTIMATED COST                                      0.21       0.21

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FILE LAST UPDATED: 19 Mar 2006  (20060319/ED)

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=> "transfer factor"
        763686 "TRANSFER"
         24820 "TRANSFERS"
        775778 "TRANSFER"
                 ("TRANSFER" OR "TRANSFERS")
        952366 "FACTOR"
        853013 "FACTORS"
       1502552 "FACTOR"
                 ("FACTOR" OR "FACTORS")
L1        2055 "TRANSFER FACTOR"
                 ("TRANSFER"(W)"FACTOR")

=> CFS
L2        1017 CFS

=> fatigure
L3          10 FATIGURE

=> Fatigue
         85734 FATIGUE
           129 FATIGUES
L4        85777 FATIGUE
                 (FATIGUE OR FATIGUES)

=> L1 and L4
L5            7 L1 AND L4

=> herpes
L6        24764 HERPES

=> L6 and l5
L7            4 L6 AND L5

=> D L4 IBIB ABS 1-4

L4   ANSWER 1 OF 85777  CAPLUS  COPYRIGHT 2006 ACS on STN
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ACCESSION NUMBER: 2006:250859 CAPLUS
TITLE: Effect of bending and mechanical damage on the physical properties of poly(p-phenylene-2,6-benzobisoxazole)(PBO) fiber
AUTHOR(S): Forster, Amanda L.; Chin, Joannie W.; Gundlach, Maureen
CORPORATE SOURCE: National Institute of Standards and Technology, Gaithersburg, MD, 20899, USA
SOURCE: Abstracts of Papers, 231st ACS National Meeting, Atlanta, GA, United States, March 26-30, 2006 (2006), POLY-274. American Chemical Society: Washington, D. C.
CODEN: 69HYEC
DOCUMENT TYPE: Conference; Meeting Abstract; (computer optical disk)
LANGUAGE: English
AB Several highly publicized vest failures over the last few years have sparked much interest in the stability of polybenzobisoxazole (PBO)-based soft body armor. Much work has been focused on the effect of heat and moisture on the degradation of PBO fibers. However, little attention has been turned to the potential for phys. damage to the vest fibers during normal daily use via sitting, standing, or other normal movement. In this study, we focus on the effect of phys. damage on the mech. properties of virgin yarn. A simple bend cycling apparatus was used to create and then relax two distinct bends in a bundle of PBO fibers. The bundle was then repeatedly cycled to **fatigue** the initial bundle damage zones. The fatigued fibers were then analyzed via dynamic mech. thermal anal. (DMTA) in transient and dynamic modes to assess their microtensile and dynamic properties. Confocal microscopy was used to characterize visible phys. damage to the bent fibers and other phys. damaged fibers. Expts. were carried out at room temperature and at 40° C (high end average use temperature). In this presentation, we discuss the effect of bend **fatigue** on the mech. and phys. properties of PBO fiber.

L4 ANSWER 2 OF 85777 CAPLUS COPYRIGHT 2006 ACS on STN
ACCESSION NUMBER: 2006:250858 CAPLUS
TITLE: Polymer/carbon nanotube composite films and fibers
AUTHOR(S): Kumar, Satish
CORPORATE SOURCE: School of Polymer, Textile and Fiber Engineering, Georgia Institute of Technology, Atlanta, GA, 30332, USA
SOURCE: Abstracts of Papers, 231st ACS National Meeting, Atlanta, GA, United States, March 26-30, 2006 (2006), POLY-273. American Chemical Society: Washington, D. C.
CODEN: 69HYEC
DOCUMENT TYPE: Conference; Meeting Abstract; (computer optical disk)
LANGUAGE: English
AB Single, double, and multiwall carbon nanotubes (CNT), and vapor grown carbon nano fibers are dispersed in polymer matrixes by insitu polymerization, in melt, and in solution These dispersions are extruded into continuous fibers by conventional melt or solution spinning. Incorporation of CNTs in polymers results in enhanced tensile strength, modulus, **fatigue** resistance, chemical resistance, glass transition temperature, and reduced thermal shrinkage. CNTs act as nucleating agent for polymer crystallization Polyacrylonitrile/CNT is a potential precursor for next generation carbon fiber. CNT and polymer/CNT films are also being processed with unique combination of tensile properties, elec. and thermal conductivity, dimensional and thermal stability, low d., and solvent resistance. Mesoporous CNT based films are being evaluated for electrochem. supercapacitor electrodes. Polymers, and polymer/CNTs are also being processed into porous nano fibers, nano wires, and microscopic cups by electrospinning. Nano fibers are being used for making bio-degradable scaffolds for tissue engineering.

L4 ANSWER 3 OF 85777 CAPLUS COPYRIGHT 2006 ACS on STN
ACCESSION NUMBER: 2006:247204 CAPLUS
TITLE: Improved underfills for copper/low-k flip chip laminate packages
AUTHOR(S): Zhang, Jack; Liu, Puwei; Ji, Qing; Shi, Gary; Todd,

Michael
CORPORATE SOURCE: Irvine R&D Center, Henkel Technologies, Irvine, CA, 92618, USA
SOURCE: Abstracts of Papers, 231st ACS National Meeting, Atlanta, GA, United States, March 26-30, 2006 (2006), IEC-193. American Chemical Society: Washington, D. C. CODEN: 69HYEC
DOCUMENT TYPE: Conference; Meeting Abstract; (computer optical disk)
LANGUAGE: English
AB Flip chip packages are gaining popularity with the increased demand of high pin count and high speed circuitry designs. Underfills have been commonly applied in organic substrate flip chip packages to couple the CTE mismatch between silicon dies and substrates, and therefore minimize the **fatigue** failure of solder bumps in thermal cycle conditions. The CTE of underfills have been formulated to closely match the CTE of solder bumps. Because of the high CTEs of traditional epoxy based resin systems, large amount of silica fillers have to be added to help lower the CTE. The glass transition temps. (Tg) of cured systems have also been designed to be high so the systems can be kept at glassy states with the low CTEs in the thermal cycle range. The moduli are therefore high as well. Such formulations have been proved to be very effective in minimize solder bump **fatigue** failures in organic packages. However, in the latest low-k dielec. flip chip packages, it is noticed that high modulus underfills could introduce more failures in low-k layer although such high modulus and low CTE formulations worked fine in traditional flip chip laminate packages. Therefore, new underfills featured with low CTEs and medium to low moduli are needed for the new low-k dielec. flip chip laminate packages. A new resin system was developed to match the requirements. Compared to traditional systems, the new system demonstrated good flowability, as well as low CTE and low modulus after cure. Such characteristics greatly reduced the dependency on fillers and gave more rooms for other formulation improvements. Finite element anal. also proved underfills based on the new resin system could lower the stresses on low-k dielec. layers while maintaining the protection on solder bumps.

L4 ANSWER 4 OF 85777 CAPLUS COPYRIGHT 2006 ACS on STN
ACCESSION NUMBER: 2006:244792 CAPLUS
TITLE: Influence of antioxidant exposure in vivo and in vitro on the biochemical markers of free radical damage in muscle
AUTHOR(S): Hayden, Edith E. W.; Cline, Paul M.; Fisher, Matthew A.
CORPORATE SOURCE: Department of Chemistry, Saint VIncent College, Latrobe, PA, 15650, USA
SOURCE: Abstracts of Papers, 231st ACS National Meeting, Atlanta, GA, United States, March 26-30, 2006 (2006), CHED-723. American Chemical Society: Washington, D. C. CODEN: 69HYEC
DOCUMENT TYPE: Conference; Meeting Abstract; (computer optical disk)
LANGUAGE: English
AB Exercise causes damage to lipids, proteins, and DNA by increasing the concentration of reactive oxygen species (ROS) that are present in cells. Vitamin E and vitamin C are two antioxidants that have been hypothesized to reduce the damage caused by ROS. This study looks at the protective effects of Vitamin E and Vitamin C, provided through dietary supplementation, on mouse skeletal muscle and plasma by measuring lipid peroxidn. and protein carbonyl formation under conditions of muscle **fatigue**. Our interest is to examine if antioxidant supplementation increases resistance to muscle **fatigue** and decreases free radical damage to muscles after **fatigue**. Protein carbonyl formation will reflect oxidative damage to muscles while lipid peroxidn. will be used as a measure of oxidative stress.